

SMD MULTILAYER COMMON MODE CHIP BEADS / WCM TYPE

FEATURES

Powerful components with composite co-fired material to solve EMI problem for high speed differential signal transmission line as USB, and LVDS without distortion to high speed signal transmission.

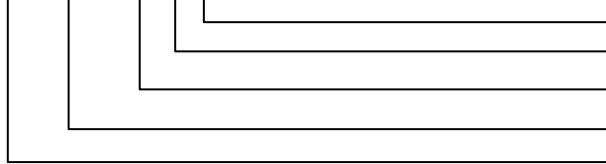


APPLICATIONS

MIPI, MHL serial interface in mobile device.

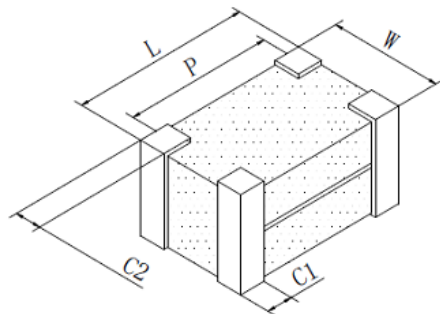
ORDERING CODE

WCM 2012 - 900 Y-N



Note: lead-free
Tolerance (Y:±25%)
Impedance
Dimension
Product Symbol

DIMENSIONS (UNIT: mm)



L	2.00 ± 0.2	m/m
W	1.25 ± 0.2	m/m
T	1.00 ± 0.1	m/m
P	1.60 ± 0.2	m/m
C1	0.4 (REF)	m/m
C2	0.3 (REF)	m/m

ELECTRICAL CHARACTERISTICS FOR WCM2012

Part No.	Impedance (Ω)	Test Frequency (MHz)	DC Resistance (Ω) Max	Rated Current (mA)Max
WCM 2012-670Y-N	67	100MHz	0.4	400
WCM 2012-900Y-N	90	100MHz	0.4	400
WCM 2012-121Y-N	120	100MHz	0.4	400
WCM 2012-161Y-N	160	100MHz	0.5	400
WCM 2012-181Y-N	180	100MHz	0.5	400
WCM 2012-221Y-N	220	100MHz	0.5	400

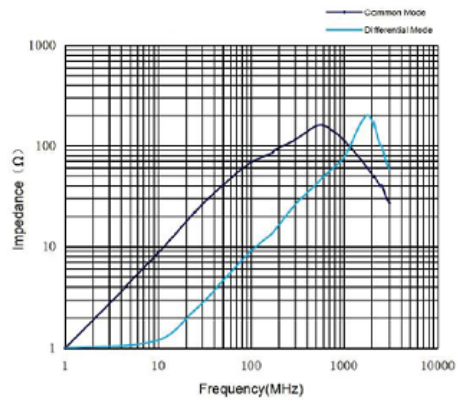
CORE MASTER ENTERPRISE CO., LTD.

<http://www.coremaster.com.tw>

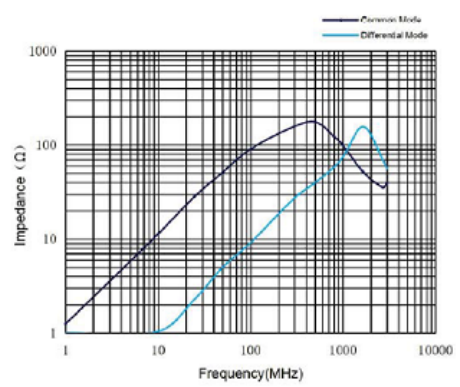


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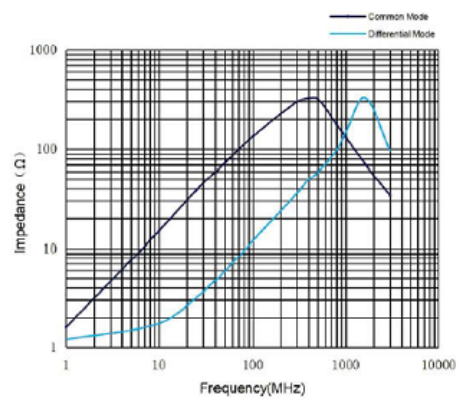
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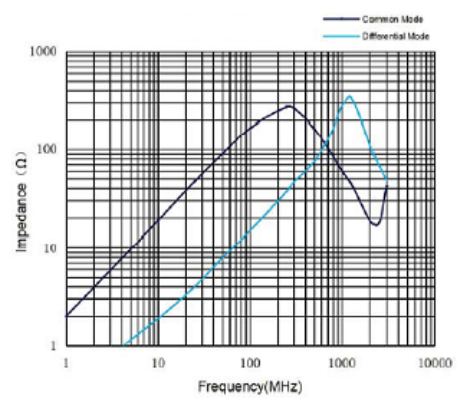
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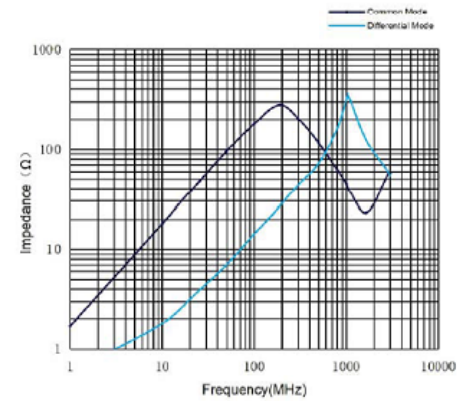
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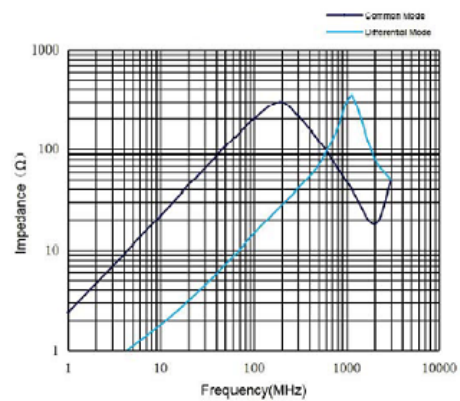
WCM 2012-161Y-N



WCM 2012-181Y-N



WCM 2012-221Y-N



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